

TABLE- 1 (Tin-Plated)

PLATING CODE	TOP PLATING THICKNESS (Min.)	UNDER PLATING THICKNESS (Min.)	AREA	MATCH TYPE
1	80μ” Tin	30μ” Nickel	Overall	Crimp clip terminal
	100μ” Tin	30μ” Nickel	Overall	Solder tail terminal & Board in
	120μ” Tin	30μ” Nickel	Overall	Square or round pin
	120μ” Tin	50μ” Nickel	Overall	SMT type terminal

TABLE- 2 (Gold -Plated)

PLATING CODE	TOP PLATING THICKNESS (Min.)	UNDER PLATING THICKNESS (Min.)	AREA	MATCH TYPE
2	0.8μ” Gold Flash Plated	50μ” Nickel	Overall	Square or round pin
	1.2μ” Gold Flash Plated	50μ” Nickel		Other type
3	15μ” Gold Plated	50μ” Nickel	Overall	All type
4	30μ” Gold Plated	50μ” Nickel	Overall	All type
5	50μ” Gold Plated	50μ” Nickel	Overall	All type
6	120μ” Min Tin over	50μ” Cu	Overall	All type
7	3μ” Gold Plated over	50μ” Nickel	Overall	All type
8	80μ” Gold Plated over	50μ” Nickel	Overall	CP35
9	5μ” Gold Plated over	50μ” Nickel	Overall	All type

A	Selective 1.2μ" Gold Flash	50μ" Nickel	Contact Area	All type
B	Selective 15μ" Gold	50μ" Nickel	Contact Area	All type
C	Selective 30μ" Gold	50μ" Nickel	Contact Area	All type
D	Selective 10μ" Gold	50μ" Nickel	Contact Area	All type
E	Selective 50μ" Gold	50μ" Nickel	Contact Area	All type
F	Selective 80μ" Gold	50μ" Nickel	Contact Area	CP35
G	Selective 5μ" Gold	50μ" Nickel	Contact Area	CCF
I	Selective 15μ" Gold	1.2μ" Gold Flash Plated over 50μ" Nickel	Contact Area	All type
J	Selective 30μ" Gold	1.2μ" Gold Flash Plated over 50μ" Nickel	Contact Area	All type

4. SOLDERABILITY:

TEST ITEM	TEST CONDITION	TEST REQUIREMENT
Solderability	Soldering time: 5±0.5 Second Soldering pot: 230±5	Minimum: 95% of immersed area